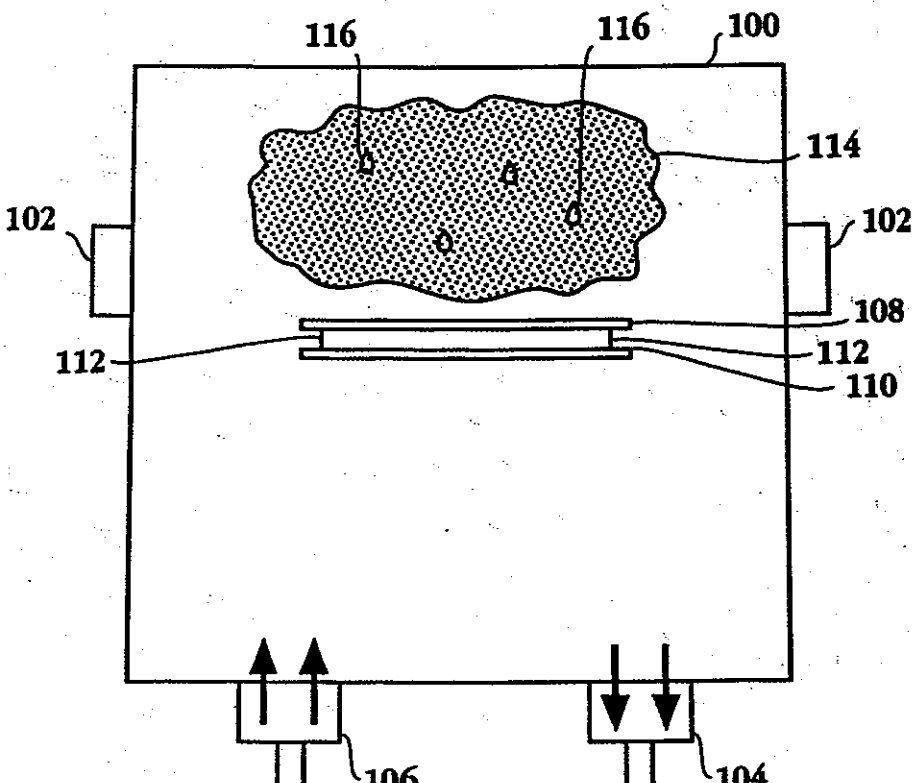


Fig. 1 (prior art)

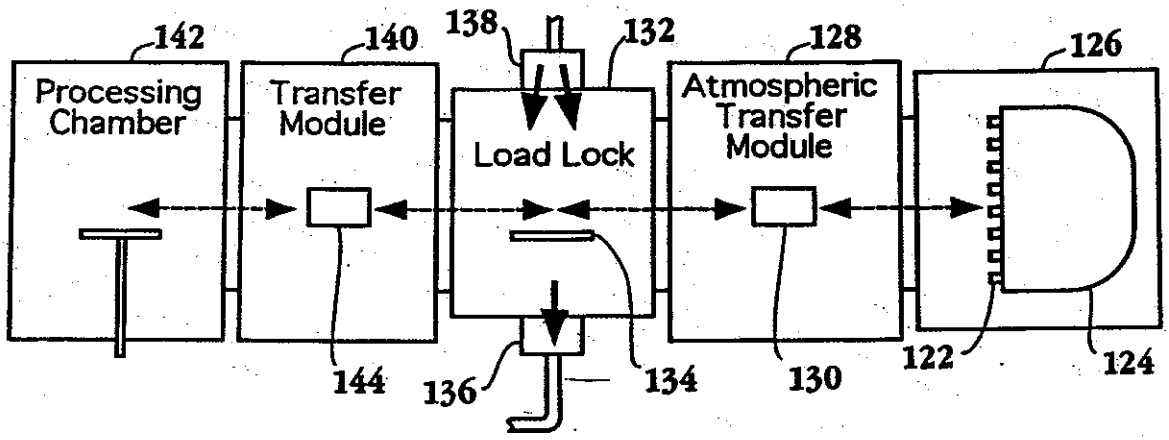

142
140
138
132
128
126
Processing Chamber
Transfer Module
Load Lock
Atmospheric Transfer Module
144
136
134
130
122
124

Fig. 2

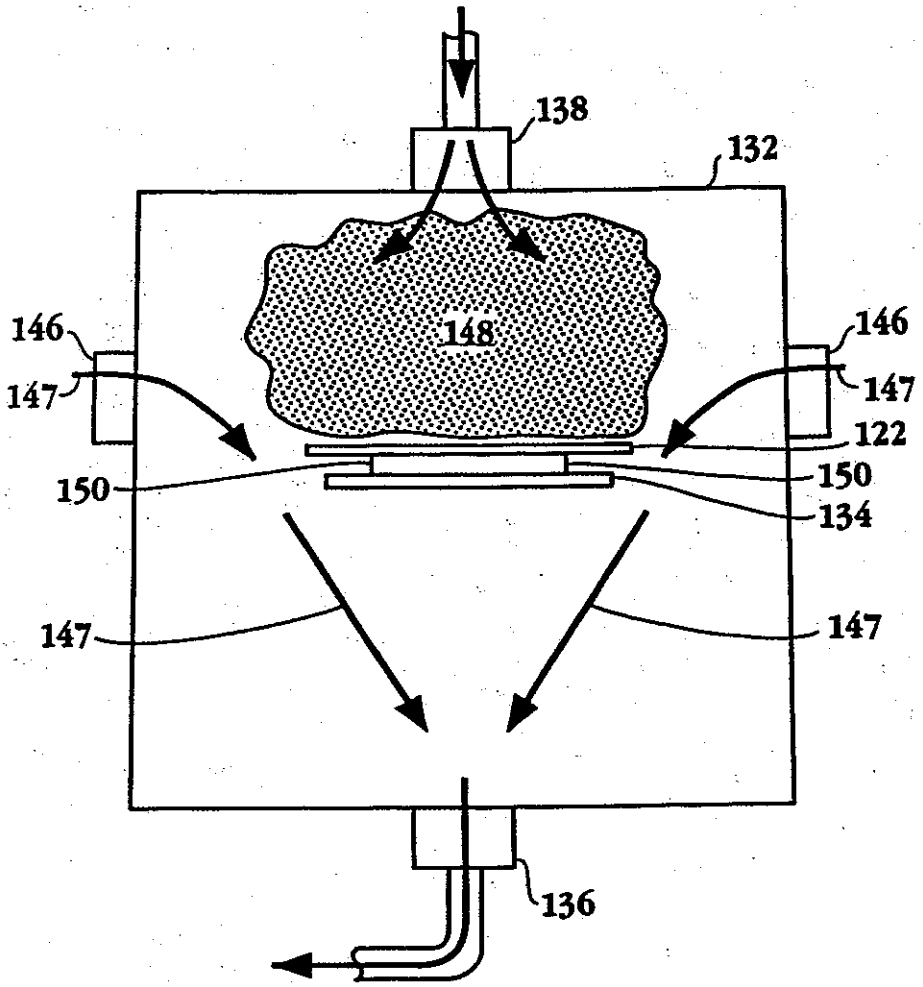

138
132
146
148
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122
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147
136

Fig. 3

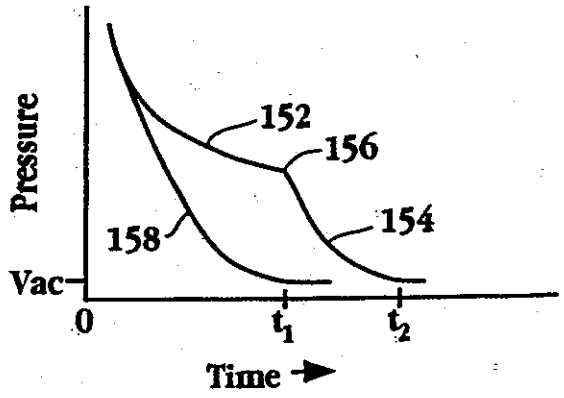

Pressure
152
156
154
158
Vac
0
t_1
t_2
Time

Fig. 4

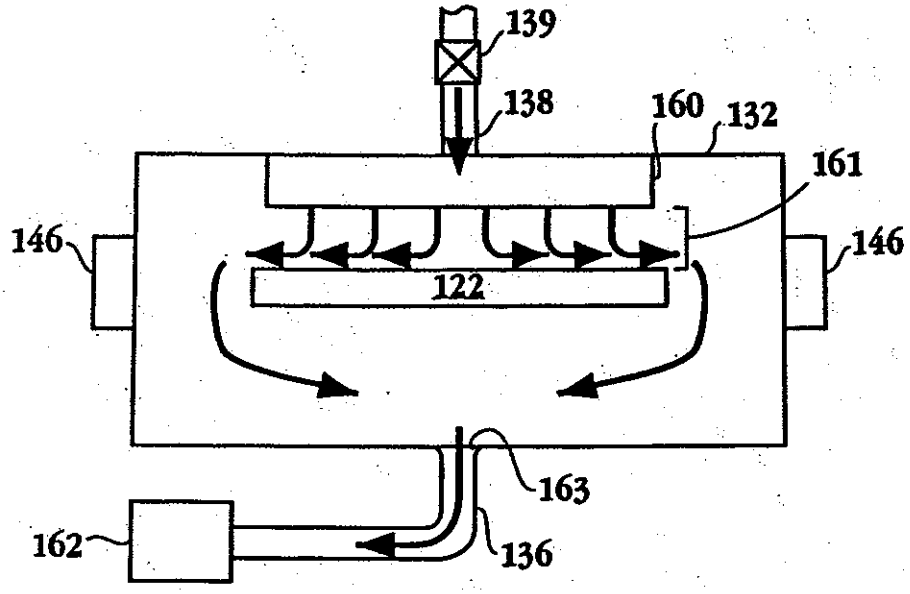

139
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160
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161
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162
136

Fig. 5

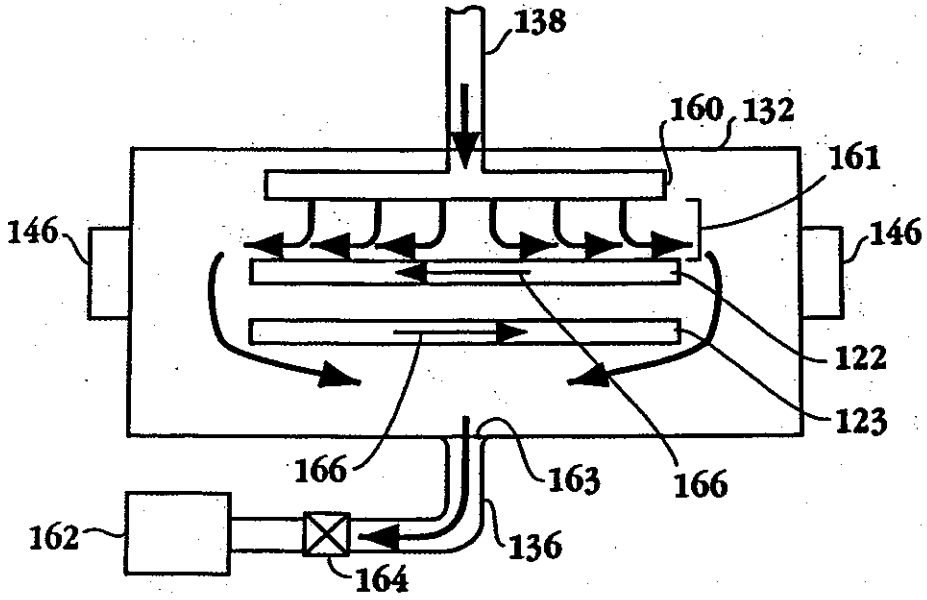

138
160
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123
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164

Fig. 6

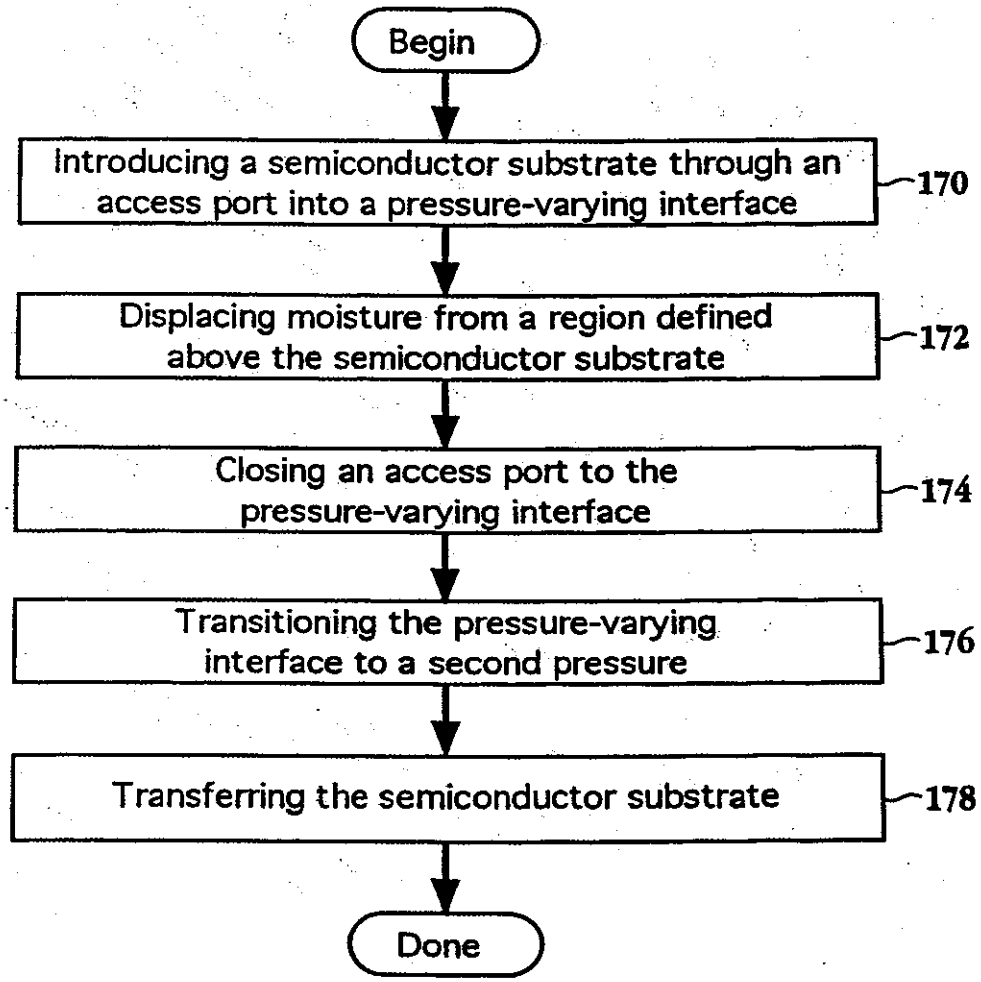

Begin
Introducing a semiconductor substrate through an access port into a pressure-varying interface
170
Displacing moisture from a region defined above the semiconductor substrate
172
Closing an access port to the pressure-varying interface
174
Transitioning the pressure-varying interface to a second pressure
176
Transferring the semiconductor substrate
178
Done

Fig. 7

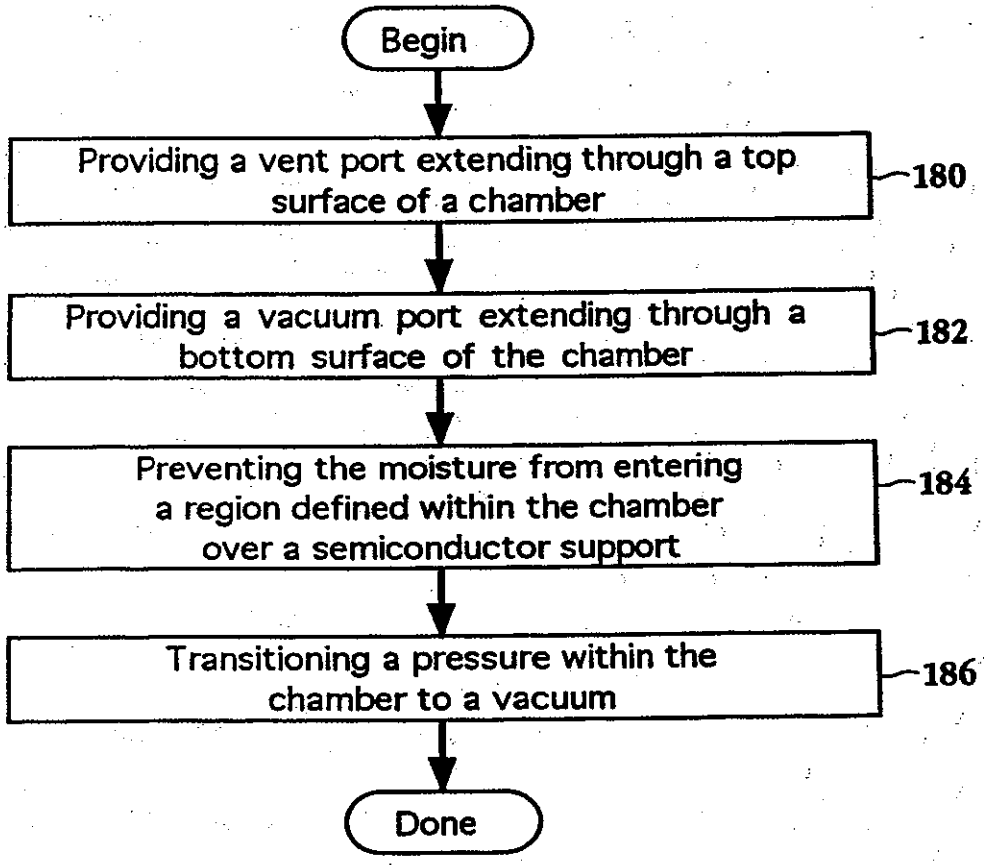

Begin
Providing a vent port extending through a top surface of a chamber
180
Providing a vacuum port extending through a bottom surface of the chamber
182
Preventing the moisture from entering a region defined within the chamber over a semiconductor support
184
Transitioning a pressure within the chamber to a vacuum
186
Done

Fig. 8